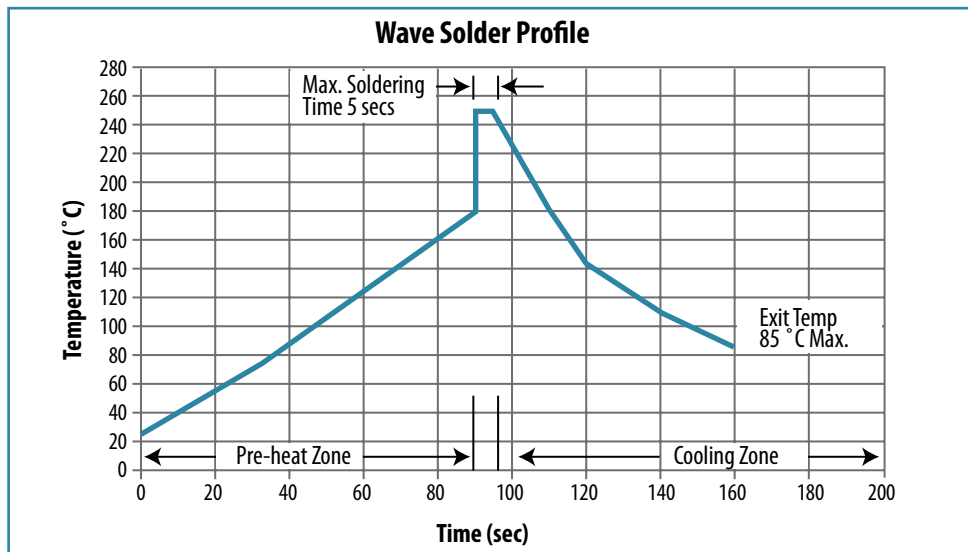


Bourns® Sensors and Controls Product Line recommends the following RoHS* single wave solder profile for through-hole commercial potentiometers and encoders as illustrated below:

- The belt speed should be adjusted per the solder equipment manufacturer's recommendations in order to insure a dwell time in the solder wave of 2 to 3 seconds.
- The solder pot temperature should be adjusted to a range of 240 °C to 250 °C.
- The flux station (foam or wave) preheat temperature should be adjusted to a range of 80 °C to 105 °C.
- The preheat temperature must not exceed 100 °C under the solder wave temperature and the preheat rate of 1.5 to 2.5 °C/sec.
- The underside PC board temperature at the last preheat zone should be approximately 150 °C.
- Verify that the difference between the solder temperature and the board is 100 °C or less at the point in time when the PC board leaves the last preheat zone.
- The PC board should be permitted to air-cool at room ambient conditions following exposure to the soldering environment. Forced air-cooling is not recommended.

Use of this recommended RoHS solder profile should optimize terminal solder wetting.



For further technical support, please visit
www.bourns.com

*RoHS Directive 2002/95/EC Jan. 27, 2003 including Annex.

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